

Molding Type Module IGBT, 2 in 1 Package, 1200 V and 400 A



Double INT-A-PAK

PRODUCT SUMMARY					
V _{CES}	1200 V				
I _C at T _C = 80 °C	400 A				
$V_{CE(on)}$ (typical) at $I_C = 400 \text{ A}$, $T_J = 25 \text{ °C}$	3.10 V				
Package	Double INT-A-PAK				
Circuit	Half bridge				

FEATURES

- 10 µs short circuit capability
- · Low switching losses
- · Rugged with ultrafast performance
- V_{CE(on)} with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

- · Inductive heating
- Switching mode power supplies
- · Electronic welder

DESCRIPTION

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welder and inductive heating.

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V _{CES}		1200	V	
Gate to emitter voltage	V _{GES}		± 20	V	
Collector current		T _C = 25 °C	660		
Collector current	lc	T _C = 80 °C	400		
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	800	Α	
Diode continuous forward current	I _F	T _C = 80 °C	400		
Diode maximum forward current	I _{FM} ⁽¹⁾	t _p = 1 ms	800		
Maximum power dissipation	P _D	T _J = 150 °C	2660	W	
Short circuit withstand time	T _{SC}	T _J = 125 °C	10	μs	
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	2500	V	

Note

⁽¹⁾ Repetitive rating: Pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL TEST CONDITIONS MIN. TYP.		MAX.	UNITS		
Collector to emitter breakdown voltage	V _{(BR)CES}	T _J = 25 °C	1200	-	-	
Collector to emitter voltage	V _{CE(on)}	$V_{GE} = 15 \text{ V}, I_{C} = 400 \text{ A}, T_{J} = 25 ^{\circ}\text{C}$	-	3.10	3.60	V
		V _{GE} = 15 V, I _C = 400 A, T _J = 125 °C	-	3.45	-	
Gate to emitter threshold voltage	V _{GE(th)}	$V_{CE} = V_{GE}$, $I_{C} = 4.0$ mA, $T_{J} = 25$ °C	4.4	4.9	6.0	
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA
Gate to emitter leakage current	I _{GES}	$V_{GE} = V_{GES}$, $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA

SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	680	-	- ns
Rise time	t _r		-	142	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, I_C = 400 \text{ A}, R_g = 2.2 \Omega,$	-	638	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 25 °C	-	99	-	
Turn-on switching loss	E _{on}		-	19.0	-	
Turn-off switching loss	E _{off}		-	32.5	-	mJ
Turn-on delay time	t _{d(on)}		-	690	-	ns ns
Rise time	t _r		-	146	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, I_C = 400 \text{ A}, R_g = 2.2 \Omega,$	-	669	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 125 °C	-	108	-	
Turn-on switching loss	E _{on}		-	26.1	-	I
Turn-off switching loss	E _{off}		-	36.7	-	- mJ
Input capacitance	C _{ies}		-	33.7	-	
Output capacitance	C _{oes}	$V_{GE} = 0 \text{ V}, V_{CE} = 30 \text{ V}, f = 1.0 \text{ MHz}$	-	2.99	-	nF
Reverse transfer capacitance	C _{res}		-	1.21	-	
SC data	I _{SC}	$\begin{array}{c} t_p \leq 10 \; \mu s, V_{GE} = 15 \; V, T_J = 25 \; ^{\circ}C, \\ V_{CC} = 600 \; V, V_{CEM} \leq 1200 \; V \end{array}$	-	2600	-	Α
Internal gate rsistance	Rg		-	0.5	-	Ω
Stray inductance	L _{CE}		=	-	18	nΗ
Module lead resistance, terminal to chip	R _{CC'+EE'}	T _C = 25 °C	=	0.32	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Forward voltage	V _F	I _F = 400 A	T _J = 25 °C	-	1.95	2.25	V
Forward voltage			T _J = 125 °C	-	1.85	-	
Poverse receivery charge	0	$\begin{array}{c} Q_{rr} \\ \\ I_{rr} \\ \\ E_{rec} \\ \end{array} \hspace{0.2cm} \begin{array}{c} I_F = 400 \text{ A, } V_R = 600 \text{ V,} \\ dI_F/dt = -2850 \text{ A/}\mu\text{s} \\ V_{GE} = -15 \text{ V} \\ \end{array} \label{eq:qr}$	T _J = 25 °C	-	24.1	-	
Reverse recovery charge	Q _{rr}		T _J = 125 °C	-	44.3	-	μC
Dools was saved week state of the state of t			T _J = 25 °C	-	220	-	۸
Peak reverse recovery current	l'rr		T _J = 125 °C	-	295	-	Α
Reverse recovery energy	Г		T _J = 25 °C	-	13.9	-	ma I
	E _{rec}		T _J = 125 °C	-	24.8	-	mJ



THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction temperature	range	TJ		-	-	150	°C
Storage temperature range		T _{Stg}		- 40	-	125	°C
Junction to case	П		-	-	0.047		
Junction to case	Diode	$R_{\theta JC}$		-	-	0.096	K/W
Case to sink (Conductive greas	e applied)	$R_{\theta CS}$		-	0.035	-	
Mounting torque			Power terminal screw: M5	2.5 to 5.0)	Nm
			Mounting screw: M6	3.0 to 6.0		INIII	
Weight			Weight of module	-	350	-	g

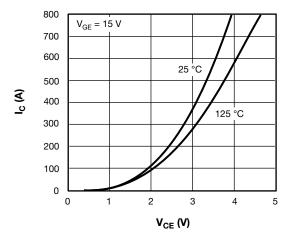


Fig. 1 - IGBT Typical Output Characteristics

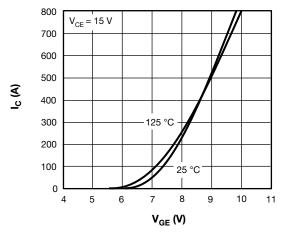


Fig. 2 - IGBT Typical Transfer Characteristics

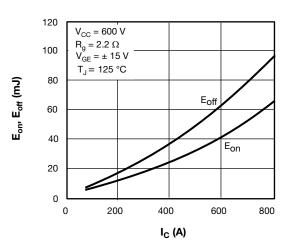


Fig. 3 - IGBT Switching Loss vs. I_C

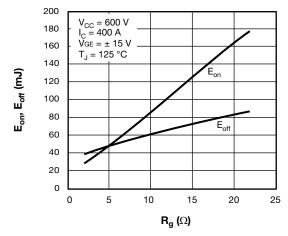


Fig. 4 - IGBT Switching Loss vs. Rg

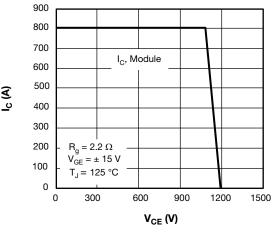


Fig. 5 - RBSOA

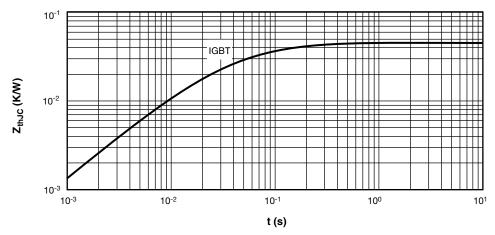


Fig. 6 - IGBT Transient Thermal Impedance

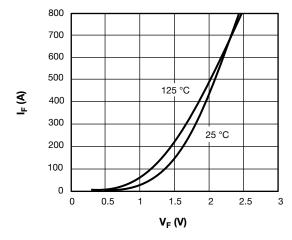


Fig. 7 - Diode Typical Forward Characteristics

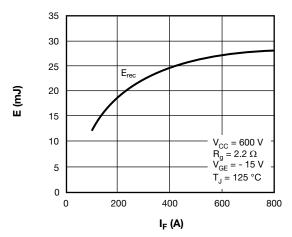


Fig. 8 - Diode Switching Loss vs. I_C

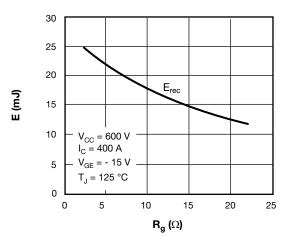


Fig. 9 - Diode Switching Loss vs. Rq

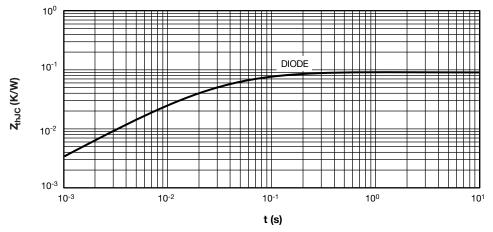
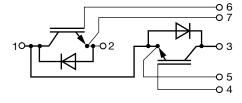


Fig. 10 - Diode Transient Thermal Impedance

CIRCUIT CONFIGURATION

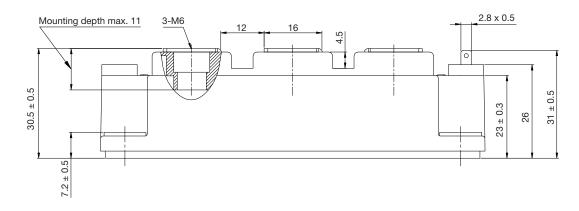


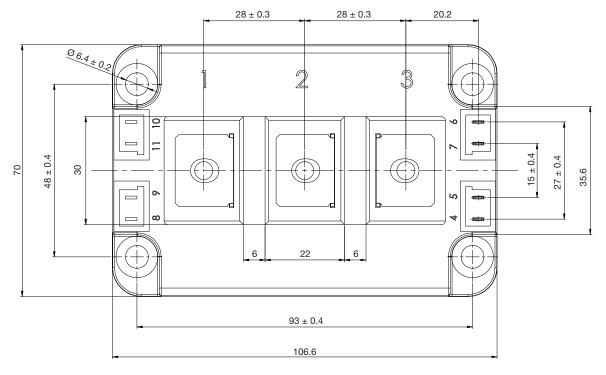
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95538			



Double INT-A-PAK

DIMENSIONS in millimeters (inches)







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Revision: 02-Oct-12 Document Number: 91000